
**UNITED STATES
SECURITIES AND EXCHANGE COMMISSION**
Washington, DC 20549

FORM 6-K

**REPORT OF FOREIGN PRIVATE ISSUER
PURSUANT TO RULE 13a-16 OR 15d-16 UNDER
THE SECURITIES EXCHANGE ACT OF 1934**

For the month of June, 2020

Commission File Number 001-37928

ChipMOS TECHNOLOGIES INC.
(Translation of Registrant's Name Into English)

**No. 1, R&D Rd. 1, Hsinchu Science Park
Hsinchu, Taiwan
Republic of China**
(Address of Principal Executive Offices)

(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F Form 40-F

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(1):

Indicate by check mark if the registrant is submitting the Form 6-K in paper as permitted by Regulation S-T Rule 101(b)(7):

SIGNATURES

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Dated: June 10, 2020

ChipMOS TECHNOLOGIES INC.

(Registrant)

By: /S/ S. J. Cheng

Name: S. J. Cheng

Title: Chairman & President

Contacts:

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**ChipMOS SHAREHOLDERS APPROVE CASH DIVIDEND DISTRIBUTION OF NT\$1.80 PER
COMMON SHARE OR APPROXIMATELY US\$1.20 PER ADS; COMPANY SETS DIVIDEND
RECORD & DISTRIBUTION DATE**

Hsinchu, Taiwan, June 10, 2020 - ChipMOS TECHNOLOGIES INC. (“ChipMOS” or the “Company”) (Taiwan Stock Exchange: 8150 and NASDAQ: IMOS), an industry leading provider of outsourced semiconductor assembly and test services (“OSAT”), announced it has submitted a dividend/distribution form to NASDAQ, as notification of the below actions for the Company’s American Depositary Shares (“ADRs”). Shareholders have approved a cash dividend distribution of NT\$1.80 per common share or approximately US\$1.20 per ADS at the Company’s AGM on June 9, 2020. The dividend, which the Company’s Board had proposed on March 10, 2020, will be distributed to shareholders from earnings.

- **Type of Distribution:** Cash Dividend
- **Declaration Date:** June 9, 2020
- **Ex-Dividend Date:** July 1, 2020
- **ADR Dividend Record Date:** July 2, 2020
- **ADR Dividend Distribution Date:** To be determined by the Depositary, Citibank NA (“Citi”), once Citi receives the distribution from the Company on July 31, 2020
- ADR books will be closed from June 30, 2020 to July 7, 2020 to coincide with the Taiwan local share book close period of July 3, 2020 to July 7, 2020
- The final dividend amount to be distributed in the United States Dollars will be determined by the Depositary, Citibank NA, once it receives the distribution from the Company on July 31, 2020, converts the amount from New Taiwan Dollars into United States Dollars and deducts appropriate taxes and fees.

S.J. Cheng, Chairman and President of ChipMOS, said, “This latest distribution continues our track record of consistently building value for investors, as we successfully execute on our business. We have maintained very healthy gross margins, utilization levels and cash flow generation, while taking a conservative approach to CapEx given market uncertainty. As a result, ChipMOS remains in a solid position with a strong balance sheet, able to fully support our customers, and both our current and long-term growth drivers.”

Questions regarding the dividend distribution may be directed to Keith Balwan (keith.balwan@citi.com) at +1.973.461.7038.

About ChipMOS TECHNOLOGIES INC.:

ChipMOS TECHNOLOGIES INC. (Taiwan Stock Exchange: 8150 and NASDAQ: IMOS) (<https://www.chipmos.com>) is an industry leading provider of outsourced semiconductor assembly and test services. With advanced facilities in Hsinchu Science Park, Hsinchu Industrial Park and Southern Taiwan Science Park in Taiwan, ChipMOS provide assembly and test services to a broad range of customers, including leading fabless semiconductor companies, integrated device manufacturers and independent semiconductor foundries.

Forward-Looking Statements

This press release may contain certain forward-looking statements. These forward-looking statements may be identified by words such as ‘believes,’ ‘expects,’ ‘anticipates,’ ‘projects,’ ‘intends,’ ‘should,’ ‘seeks,’ ‘estimates,’ ‘future’ or similar expressions or by discussion of, among other things, strategy, goals, plans or intentions. These statements may include financial projections and estimates and their underlying assumptions, statements regarding plans, objectives and expectations with respect to future operations, products and services, and statements regarding future performance. Actual results may differ materially in the future from those reflected in forward-looking statements contained in this document, due to various factors, including the potential impact of COVID-19. Further information regarding these risks, uncertainties and other factors are included in the Company’s most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange Commission (the “SEC”) and in the Company’s other filings with the SEC.